

# High-Speed Switching Diode

## MMDL914T1

ON Semiconductor Preferred Device

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Reverse Voltage	$V_R$	100	Vdc
Forward Current	$I_F$	200	mAdc
Peak Forward Surge Current	$I_{FM(surge)}$	500	mAdc

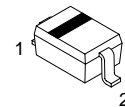
### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board,* $T_A = 25^\circ\text{C}$ Derate above $25^\circ\text{C}$	$P_D$	200	mW
		1.57	mW/ $^\circ\text{C}$
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	635	$^\circ\text{C}/\text{W}$
Junction and Storage Temperature	$T_J, T_{stg}$	150	$^\circ\text{C}$

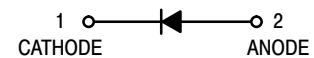
\*FR-4 Minimum Pad

### DEVICE MARKING

MMDL914T1 = 5D



CASE 477-02, STYLE 1  
SOD-323

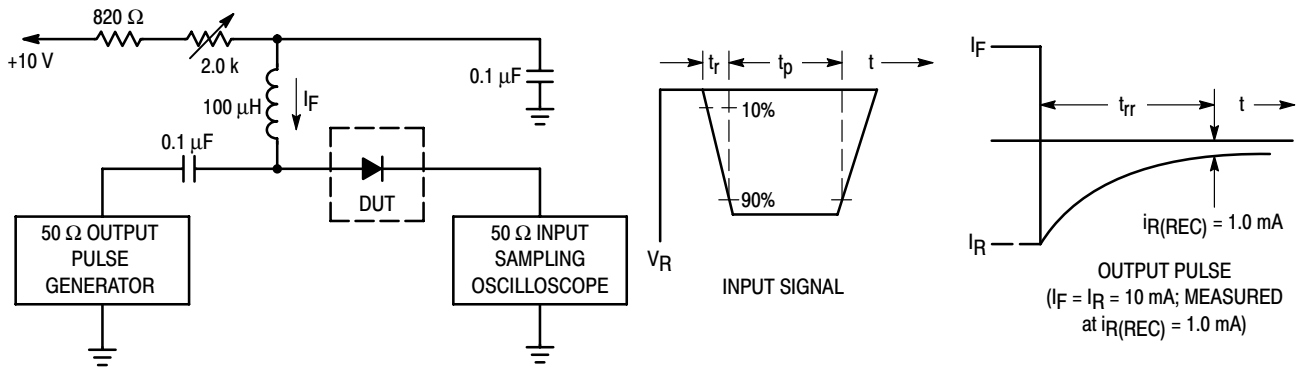


### ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ unless otherwise noted)

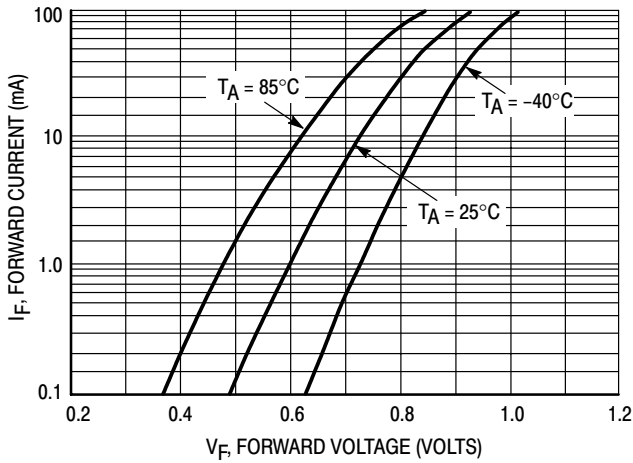
Characteristic	Symbol	Min	Max	Unit
<b>OFF CHARACTERISTICS</b>				
Reverse Breakdown Voltage ( $I_R = 100 \mu\text{Adc}$ )	$V_{(BR)}$	100	–	Vdc
Reverse Voltage Leakage Current ( $V_R = 20 \text{Vdc}$ ) ( $V_R = 75 \text{Vdc}$ )	$I_R$	–	25 5.0	nAdc $\mu\text{Adc}$
Diode Capacitance ( $V_R = 0, f = 1.0 \text{MHz}$ )	$C_T$	–	4.0	pF
Forward Voltage ( $I_F = 10 \text{mAdc}$ )	$V_F$	–	1.0	Vdc
Reverse Recovery Time ( $I_F = I_R = 10 \text{mAdc}$ ) (Figure 1)	$t_{rr}$	–	4.0	ns

Preferred devices are ON Semiconductor recommended choices for future use and best overall value.

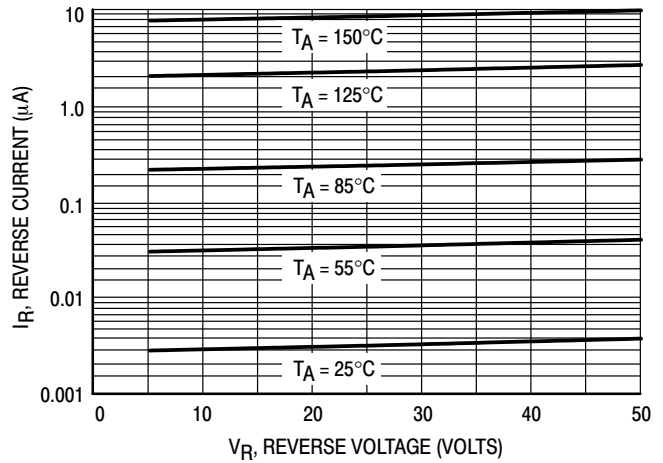
# MMDL914T1



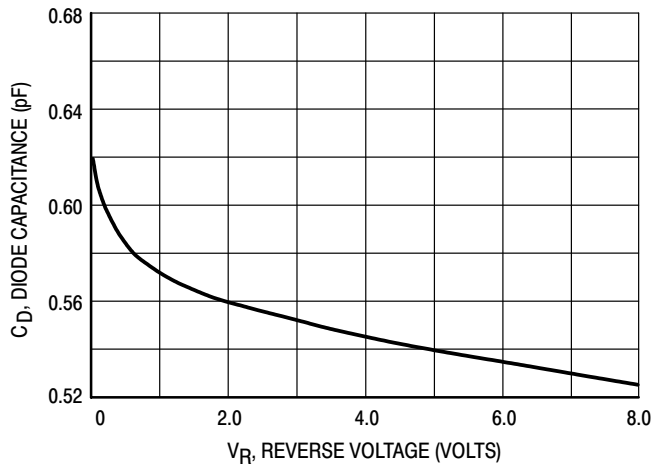
**Figure 1. Recovery Time Equivalent Test Circuit**



**Figure 2. Forward Voltage**



**Figure 3. Leakage Current**

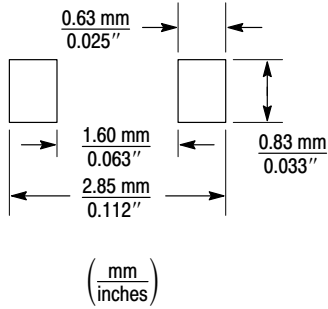
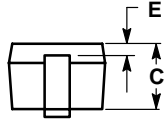
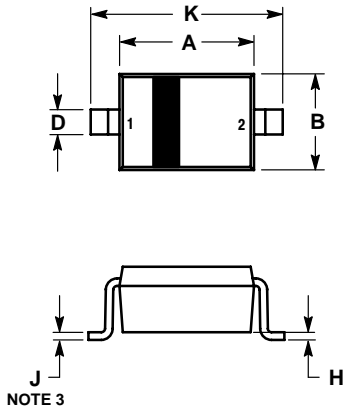


**Figure 4. Capacitance**

# MMDL914T1

## PACKAGE DIMENSIONS

SOD-323  
CASE 477-02  
ISSUE B




- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.60	1.80	0.063	0.071
B	1.15	1.35	0.045	0.053
C	0.80	1.00	0.031	0.039
D	0.25	0.40	0.010	0.016
E	0.15 REF		0.006 REF	
H	0.00	0.10	0.000	0.004
J	0.089	0.177	0.0035	0.0070
K	2.30	2.70	0.091	0.106

- STYLE 1:  
PIN 1. CATHODE  
2. ANODE

SOD-323  
Soldering Footprint

Thermal Clad is a trademark of the Bergquist Company.

**ON Semiconductor** and  are trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer.

## PUBLICATION ORDERING INFORMATION

### Literature Fulfillment:

Literature Distribution Center for ON Semiconductor  
P.O. Box 5163, Denver, Colorado 80217 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** ONlit@hibbertco.com

**N. American Technical Support:** 800-282-9855 Toll Free USA/Canada

**JAPAN:** ON Semiconductor, Japan Customer Focus Center  
4-32-1 Nishi-Gotanda, Shinagawa-ku, Tokyo, Japan 141-0031  
**Phone:** 81-3-5740-2700  
**Email:** r14525@onsemi.com

**ON Semiconductor Website:** <http://onsemi.com>

For additional information, please contact your local Sales Representative.